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TITLE : SOLDER AND METHOD OF MOUNTING ELECTRONIC PARTS

ABSTRACT : PROBLEM TO BE SOLVED: To improve thermal fatigue property of a soldered part in comparison with addition of Cu alone by adding not more than a specific quantity of at least P or B to the composition consisting of a specific weight % each of Sn, Cu, and Pt and the balance Pb.

SOLUTION: The solder is constituted in weight% of 5.0-95.0 Sn, 0.1-3.0 Cu, 0.05-2.0 Pt and the balance Pb, with at least P or B added by 0.3 pts.wt. or less against total 100 pts.wt. The mounting method of electronic parts is such that electronic parts having electroless Ni plated surface particularly silicon chips and substrate mounted with other electronic parts are connected with the solder. The reason of making an Sn-Pb system as the base is that it can be used in mounting semiconductor parts having low heat resistance. In addition, even if the surface to be jointed is an electroless Ni plated surface, it can be soldered appropriately.

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